

AUTOMOTIVE RANGE

Solder Wire (Sn60Pb40)



Application

- This product is suitable for hand Soldering Process in Electronic & Electrical Assembly. Soldering Iron Set temperature ranging from 350°C to 425°C is recommended to get desired Solder Joints. Solder wire is designed with Flux Cored and Residue may form on Joints which may not contribute any impact to Circuit Assemblies. Cleaning should be done when Rosin Cored Solder Wire is used.
- Soldering Wires conforms to JIS, ANSI, IPC, DIN, ISO Standards.

Item No.	Description	Weight (g)
SOL0.5	Solder Wire 26 SWG / 0.46 mm	250
SOL3	Solder Wire 22 SWG / 0.71 mm	500
SOL4	Solder Wire 18 SWG / 1.22 mm	500

Technical Details:

Product Description

- High purity Alloy that is composed of 60% Tin and 40% Lead from Virgin Metals.
- Applied by Hand or Feed Soldering Process in Electronic & Electrical Assemblies.
- Non-Corrosive and No Impact of Residue form at Post Soldering which means passes in Pin Probe & Flying Probe Tests for No Clean Wires.
- If require residue shall clean with appropriate Liquid Application.
- Precise amount of Flux cored from state of the art Technology Process.

Storage And Handling

- Do not Fire anything near storage area.
- Store in Dry, Cool and Non-Corrosive environment.
- Wear Personal Protective Equipments while Handling.
- Wear Personal Protective Equipments while Processing.

Product Specification

No.	Item	Specification	Standard
1	Appearance	Bright and shiny finishes	NA
2	Alloy	Sn/Pb60	JIS-Z-3282 A CLASS
3	Melting Point	183°C	DSC
4	Flux Content	1.3%, 1.8%, 2.2% ±0.1 %	JIS-Z-3283
5	Flux Type	F4, R, RC	NA
6	Packaging	500gm	
7	Diameter	Up to 30 SWG	JIS-Z-3283
8	Features	Excellent solder joint reliability. Superior joint strength. Excellent thermal & Mechanical fatigue resistance. Low cleaning required after solder joint	
9	Purpose	For use in applications requiring good activation.	

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Physical Properties

No.	Test Item	Test Result	Test Method
1	Silver Chromate Test	PASS	IPC-TM-650, 2.6.33
2	Copper Mirror Test	PASS	IPC-TM-650, 2.6.32
3	Copper plate Corrosion	PASS	JIS-Z-3197, 6.6.1
4	S.I.R Test	1x10 ⁹ up	IPC-TM-650, 2.6.3.3
5	Electro migration Test	1x10 ¹¹² up	IPC-TM-650, 2.6.14.1

Alloy Composition

(Sn)	(Pb)	(Sb)	(Cu)	(Bi)	(Zn)	(Fe)	(Al)	(As)	(Cd)
REM	39.5-40.5	0.12 MAX	0.05 MAX	0.10 MAX	0.002 MAX	0.02 MAX	0.002 MAX	0.03 MAX	0.002 MAX